

Amendments to the Claims

1. *(Currently Amended)* A structure (10, 20)-comprising at least one proportional variable resistor (24)-suitable for electrically measuring unidirectional misalignment of stitched masks in etched interconnect layers, said structure comprising at least a first mask (10) and a second mask (20)-that when superimposed comprise at least two test pads (14, 16) and interconnects (12, 22) the resistance between (24)-which can be measured.
2. *(Original)* The invention according to claim 1 comprising at least one directly proportional variable resistor.
3. *(Original)* The invention according to claim 1 comprising at least one inversely proportional variable resistor.
4. *(Currently Amended)* The invention (30, 50)-according to claim 1 comprising at least one stick type (32, 24, 36, 38)-interconnect.
5. *(Currently Amended)* The invention according (60, 70)-to claim 1 comprising at least one hook type interconnect (62, 72).
6. *(Original)* A system for electrically measuring unidirectional misalignment of stitched masks in etched interconnect layers, said system comprising at least one proportional variable resistor comprising a reference mask comprising at least two test pads and a second mask comprising at least one interconnect; and a probe for testing the resistance between said interconnect of said reference mask and said interconnect of said second mask when said masks are superimposed.
7. *(Original)* The invention according to claim 6, the at least one interconnect of said reference mask comprising at least one stick type interconnect.
8. *(Original)* The invention according to claim 6, the at least one interconnect of said reference mask comprising at least one hook type interconnect.
9. *(Original)* The invention according to claim 6, the at least one interconnect of said second mask comprising at least one stick type interconnect.
10. *(Original)* The invention according to claim 6, the at least one interconnect of said second mask comprising at least one hook type interconnect.
11. *(Original)* The invention according to claim 6, said system comprising at least one inversely proportional variable resistor.
12. *(Original)* The invention according to claim 6, said system comprising at least one directly proportional variable resistor.
13. *(Original)* A method of measuring stitched mask misalignment in etched interconnect layers comprising the steps of: providing a reference mask comprising at least two test pads; providing a second mask comprising at least one interconnect; superimposing said reference

mask and said second mask to provide at least one proportional variable resistor; electrically measuring the resistance of said at least one proportional variable resistor.

14. (*Original*) The method according to claim 13 further comprising the step of establishing an optimum resistance between said test pads.

15. (*Original*) The invention according to claim 14 comprising the further steps of comparing a measured resistance to said optimum resistance and adjusting the position of said masks to alignment.